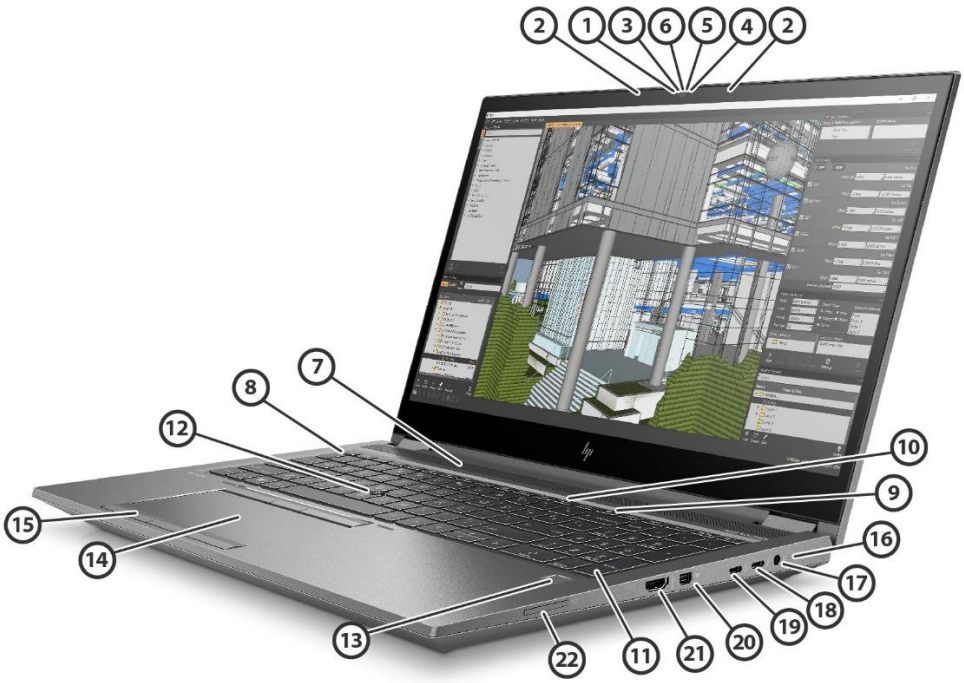
Overview

HP ZBook Fury 15 G8 Mobile Workstation



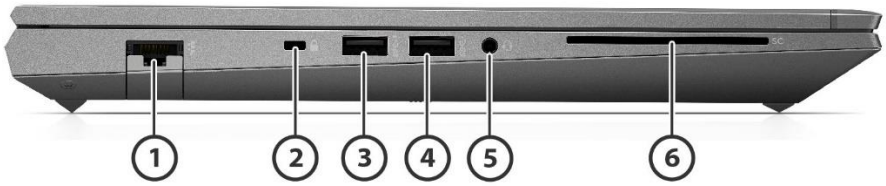
1. Ambient Light Sensor
2. Internal Microphones (optional)
3. Camera LEDs (optional)
4. HD Camera (optional)
5. IR Camera (optional)
6. Camera Cover (optional)
7. Speakers with Discrete Amplifier
8. Function Keys (changes with configured options)
9. Power button
10. HP Programmable Key
11. Numeric Keypad
12. Pointstick

Right

13. Fingerprint Sensor (optional)
14. Touchpad
15. 3-button Touchpad
16. Indicator LEDs: Power light, Wireless light, Storage usage light
17. Power connector
18. USB Type-C® with Thunderbolt™ 4[1]
19. USB Type-C® with Thunderbolt™ 4[1]
20. Mini DisplayPort™
21. HDMI port
22. SD Card Reader

[1]SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4.

Overview



Left

1. RJ-45
2. Nano security lock slot
3. USB 3.1 Gen 1 Charging Port
4. USB 3.1 Gen 1
5. Audio Combo Jack
6. Smart Card Reader

Overview

At A Glance

- Work anywhere without compromising on performance or security with Windows 10 Pro [1], powered by HP's collaboration and connectivity technology.
- Accelerate your workflow. Power through projects with up to 128 GB RAM [2] for fast rendering, editing and visual effects performance.
- Take multitasking to the next level with the Intel® Core™ i9 processor [3] designed to handle complex, multithreaded apps like Adobe® Premier Pro, and with fast clock speeds you can boost your speed on single threaded apps like Autodesk 3ds Max.[4]
- Run demanding professional apps with the newest generation Intel® Xeon® processors [5] for powerful performance and productivity.
- Experience high-end visualization and seamlessly render your biggest projects with the next generation NVIDIA® Ampere architecture with NVIDIA® T-Series and RTX A graphics[19]; Certified and supported for the apps you use every day.
- Strenuously tested to meet software certification and deliver superb performance with leading software providers, including Autodesk and Adobe® [6].
- Blitz through multiple tasks and ditch external drives with up to 8 TB [7], local PCIe NVMe storage - up to 21x faster than standard HDD and 6x faster than SATA SSD [9].
- Instantly protect against visual hacking with HP Sure View [10], and defend against firmware and malware attacks with HP Sure Start [11] and HP Sure Sense [12], and have peace of mind with multi-factor authentication- including an infrared camera and fingerprint scanner [13].
- Enhanced transfer and upload speeds via dual Thunderbolt™ 4 ports. Get wide-ranging connectivity options to ensure maximum device interaction: USB 3.0, HDMI, mDP, SD card, Smart Card Reader and more.
- Designed for ultimate durability, this ZBook undergoes brutal MIL-STD 810H [14] tests to help ensure this PC keeps rolling through your workday.
- Plug in to greater connectivity at your desktop with the HP Thunderbolt Dock for lightning-fast Thunderbolt™ 4 [15] transfers and the flexibility to run more than up to 2 external 4k [16,17].
- Improve connectivity while on Wi-Fi® with HP Extended Range Wireless LAN that allows greater distance from transmission point and fast data throughput at shorter ranges [18].

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Features

OPERATING SYSTEM

Preinstalled OS	Windows 10 Pro 64 - HP recommends Windows 10 Pro for business.[1] Windows 10 Pro for Workstations 64[1] Windows 10 Home 64[1] Windows 10 Home Single Language 64[1] FreeDOS 3.0 Ubuntu Linux 20.04[2]
Web support OS	Red Hat® Enterprise Linux® 8[2] Windows 10 Enterprise 64[1]
Supported Version	For testing information on newer versions of Windows 10, please see: https://support.hp.com/document/c05195282.

[1] Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.
[2] For detailed Linux® OS/hardware support information, see: http/www.hp.com/linux_hardware_matrix

PROCESSOR

11th Generation Intel® Xeon® W-11955M vPro® with Intel® UHD Graphics (2.6 GHz base frequency, up to 5.0 GHz with Intel® Turbo Boost Technology, 24 MB cache, 8 cores)[1,2,3,4,5]

11th Generation Intel® Core™ i9-11950H vPro® with Intel® UHD Graphics (2.6 GHz base frequency, up to 5.0 GHz with Intel® Turbo Boost Technology, 24 MB cache, 8 cores) [1,2,3,4,5]

11th Generation Intel® Core™ i9-11900H with Intel® UHD Graphics (2.5 GHz base frequency, up to 4.9 GHz with Intel® Turbo Boost Technology, 24 MB L3 cache, 8 cores) [1,2,3,4,5]

11th Generation Intel® Core™ i7-11850H vPro® with Intel® UHD Graphics (2.5 GHz base frequency, up to 4.8 GHz with Intel® Turbo Boost Technology, 24 MB L3 cache, 8 cores) [1,2,3,4,5]

11th Generation Intel® Core™ i7 11800H with Intel® UHD Graphics (2.3 GHz base frequency, up to 4.6 GHz with Intel® Turbo Boost Technology, 24 MB L3 cache, 8 cores)[1,2,3,4,5]

11th Generation Intel® Core™ i5-11500H vPro® with Intel® UHD Graphics (2.9 GHz base frequency, up to 4.6 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 6 cores)[1,2,3,4.5]

[1] Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
[2] Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
[3] Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. Energy Efficient Turbo is a power management feature that can lower the maximum core ratio (frequency), if the CPU thinks it can achieve about the same performance as with the maximum turbo frequency. Energy Efficient Turbo feature is disabled in Comet Lake H in order to prioritize performance in DC mode. It can be changed in F10 BIOS settings. See www.intel.com/technology/turboboost for more information.[4] In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.
[5] For full Intel® vPro® functionality, Windows 10 Pro 64 bit, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or WLAN card and TPM 2.0 are required. Some functionality requires additional 3rd party software in order to run. See http://intel.com/vpro

Features

CHIPSET

Mobile Intel® TigerLake PCH-H, WM 590

INTEL® CORE™ I5 WITH VPRO/CORE I7 WITH VPRO/XEON® WITH VPRO TECHNOLOGY CAPABLE

Intel® Core™ i5 with vPro™, Core™ i7 with vPro™, Core™ i9 with vPro™ and Xeon® with vPro™ technology is a selectable feature that is available on units configured with select processors, a qualified Intel® WLAN module and a preinstalled Windows® operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel® Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update regardless of their power state. [1,2]

[1] Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.
[2] For full Intel® vPro® functionality, Windows 10 Pro 64 bit, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or WLAN card and TPM 2.0 are required. Some functionality requires additional 3rd party software in order to run. See http://intel.com/vpro

GRAPHICS

Integrated

Intel® UHD Graphics [1,2,3,4,5]

Discrete

NVIDIA Graphic options:

NVIDIA RTX™ A5000 (16 GB GDDR6 dedicated)[1,2,3,4,5,7]

NVIDIA RTX™ A4000 (8 GB GDDR6 dedicated)[1,2,3,4,5,7]

NVIDIA RTX™ A3000 (6 GB GDDR6 dedicated)[1,2,3,4,5,7]

NVIDIA RTX™ A2000 (4 GB GDDR6 dedicated)[1,2,3,4,5]

NVIDIA® T1200 (4 GB GDDR6 dedicated) [1,2,3,4,5]

AMD Graphic options:

AMD Radeon Pro W6600M (8 GB GDDR6 dedicated) [1,2,3,4,5,7]

[1] UHD content required to view UHD images.
[2] Support HD decode, DX11, DX12, HDMI 2.0b, HDCP 2.3 via DP up to 4K @ 60Hz and via HDMI up to 4K @ 60Hz (NVIDIA RTX™ A5000, RTX A4000, RTX A3000, RTX A2000, AMD Radeon Pro W6600M support HDMI 2.1 with FRL)
[3] HDMI cable Sold Separately
[4] Shared video memory (UMA) uses part of the total system memory for video performance. System memory dedicated to video performance is not available for other use by other programs.
[5] miniDP cable sold separately.
[6] GPU configurations may be limited to specific panel options
[7] The HP custom vapor chamber (Z VaporForce) is only available on configurations with NVIDIA® RTX™ A3000 graphics and greater or AMD Radeon graphics

Multi Display Support

Features

Without HP Thunderbolt™ Dock G2

UMA Graphics: Unit supports up to 3 independent displays. Any combination of displays outputs may be used except one of Thunderbolt™ 4 and HDMI.
Hybrid Graphics (NVIDIA): Unit supports up to 4 independent displays. Any combination of displays outputs may be used except when using one USBC and HDMI are exclusive

Hybrid Graphics (AMD): Unit supports up to 4 independent displays. Any combination of displays outputs may be used except when using one USBC and HDMI are exclusive

NOTE: If Thunderbolt™ only port on the dock is connected, then the three external displays will not function.

With HP Thunderbolt™ Dock G2

UMA Graphics: Unit supports up to 3 independent displays. Any combination of displays outputs may be used except one of Thunderbolt™ 4 and HDMI.
Hybrid Graphics (NVIDIA): Unit supports up to 4 independent displays. Any combination of displays outputs may be used except when using one USBC and HDMI are exclusive

Hybrid Graphics (AMD): Unit supports up to 6 independent displays. Any combination of displays outputs may be used except when using one USBC and HDMI are exclusive

NOTE: Resolutions are dependent upon monitor capability and resolution and color depth settings.

DISPLAY

Non-touch

- 15.6" diagonal FHD (1920 x 1080) IPS eDP1.2 anti-glare WLED-backlit and ambient light sensor 250 nits 45% CG[1,2]
- 15.6" diagonal FHD (1920 x 1080) IPS eDP1.3 + PSR anti-glare WLED-backlit and ambient light sensor 400 nits 72% CG [1,2]
- 15.6" diagonal FHD (1920 x 1080) IPS eDP1.3 + PSR anti-glare WLED-backlit and ambient light sensor 1000 nits 72% CG Next Gen HP SureView Reflect [1,2,5,7]
- Next Gen HP Dream Color display 15.6" diagonal UHD (3840 x 2160) IPS 120Hz eDP1.4 + PSR2 anti-glare BV LED-backlit and ambient light sensor 600 nits 100% DCI-P3[1,2,3]

Touch

- 15.6" diagonal UHD (3840 x 2160) IPS eDP1.4 + PSR2 WLED-backlit touch screen with Corning® Gorilla® Glass 5 and ambient light sensor 600 nits 100% DCI-P3 [1,2,3,7]

HP Virtual Reality[6] Headset (sold separately)

- HP Reverb
- HP Reverb G2

[1] UHD content required to view UHD images.
[2] Resolutions are dependent upon monitor capability, and resolution and color depth settings.
[3] Display options may be limited to specific GPU Configurations.
[5] HP Sure View Reflect is optional and must be configured at purchase.
[6] Virtual Reality content is required to view Virtual Reality images
[7] Actual brightness will be lower with Sure View or touchscreen.

Features

STORAGE AND DRIVES*

Max Storage
8TB through four M.2 NVMe drives
6TB through two M.2 NVMe drives and one 2.5" SATA drive

(up to 1) HDD Storage (SATA 3.2)[4]
500 GB 7200 rpm SATA FIPS 140-2 SED HDD
500 GB 7200 rpm SATA HDD
1 TB 7200 rpm SATA HDD
2 TB 5400 rpm SATA HDD

(up to 4) M.2 Storage (NVMe™ PCIe SSD)

256 GB PCIe (NVMe™) TLC Solid State Drive
256 GB PCIe (NVMe™) TLC Self Encrypting (SED) Solid State Drive
512 GB PCIe (NVMe™) TLC Solid State Drive
512 GB PCIe (NVMe™) TLC Self Encrypting (SED) Solid State Drive
1 TB PCIe (NVMe™) TLC Solid State Drive[3]
1 TB PCIe (NVMe™) TLC Self Encrypting (SED) Solid State Drive
2 TB PCIe (NVMe™) TLC Solid State Drive[3]
2 TB PCIe (NVMe™) TLC Self Encrypting (SED) Solid State Drive

256 GB PCIe Gen4 (NVMe™) TLC Solid State Drive**
256 GB PCIe Gen4 (NVMe™) TLC Self Encrypting (SED) OPAL2 Solid State Drive**
512 GB PCIe Gen4 (NVMe™) TLC Solid State Drive**
512 GB PCIe Gen4 (NVMe™) TLC Self Encrypting (SED) OPAL2 Solid State Drive**
1 TB PCIe Gen4 (NVMe™) TLC Solid State Drive**
2 TB PCIe Gen4 (NVMe™) TLC Solid State Drive**

[1]Storage slot 1-4 can support NVMe protocol
[2]Storage slot 1, 3 and 4 can support SATA protocol
[3]Only storage slots 1-3 can support RAID
[4]System is preset to Modern Standby Disconnected with factory preinstall image

* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35GB of disk is reserved for system recovery software.
** Available late September 2021.

DRIVE CONTROLLERS

M.2 Storage Bay (PCIe NVMe)	PCIe Gen 3 x 4 lanes NVMe Solid State Drive
RAID:	RAID 0 and RAID 1 support[1]

[1] Support only available with 1TB + 1TB M.2 storage or 2TB + 2TB M.2 storage combinations
[2] Not available if slots if storage slots 3 or 4 are selected

MEMORY

Maximum Memory[2,3,5]
128 GB DDR4-3200 non-ECC SDRAM DIMM1, DIMM3, DIMM2, DIMM4
64 GB DDR4-3200 ECC SDRAM
4 DDR4 SODIMMS[4]
Supports Dual Channel Memory[1]
Slots are customer accessible / upgradeable

Features

[1]Maximized dual-channel performance requires SODIMMs of the same size and speed in both memory channels.
[2] Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.
[3]Transfer rates up to 3200 MT/s for nECC and ECC memory combinations when memory suppliers are consistent. If suppliers are not consistent, speeds may drop to 2933 MT/s for nECC and 2933 MT/s for ECC memory combinations. A custom configuration including part number AY104AV can be used to lock in a consistent vendor.
[4]Intel® allows architectures designed with four DIMM slots to run at 3200 MT/s
[5]Maximum memory capacities assume Windows 64-bit operating systems. With Windows 32-bit operating systems, memory above 3 GB may not all be available due to system resource requirements.

Features

NETWORKING/COMMUNICATIONS

LAN

Intel® I219-LM GbE, vPro™[1]
Intel® I219-V GbE, non-vPro™[1]

[1]GbE - The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

WLAN

Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5.2 combo, vPro™ [1]
Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5.2 combo, non-vPro™ [1,2]

[1]Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited. Only available in countries where 802.11ax is supported.

[2] Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.

WWAN[1]

Intel® XMM™ 7360 LTE Advanced CAT 9[3]

Nano SIM card slot[2,3]

A removable SIM is an orderable option for selected 4G LTE notebooks. The removable physical eSIM is placed on the SIM tray on the notebook like a standard SIM card. The removable eSIM is programmable and is not limited to a single carrier. You must add eSIM profile to connect to the internet using cellular data.

[1] WWAN use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, and in all regions.

[2] All units have an internal SIM card slot but 'For WWAN' base units ship with antennas.
[3] Works with Windows 10 only.

Optional Near Field Communication (NFC) module

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen, dual stereo speakers, HP World Facing Microphone dual array digital microphone[1], functions keys for volume up and down, combo microphone/headphone jack, HD audio

[1]Dual-microphone array when equipped with optional webcam and optional world facing microphone.

Camera[1, 2, 3]

720p HD webcam with IR
720p HD webcam

[1] FHD and HD content required to view HD images respectively.

Features

[2] Windows Hello face authentication utilizes a camera specially configured for near infrared (IR) imaging to authenticate and unlock Windows devices as well as unlock your Microsoft Passport.
[3]Camera-configured options come with a Privacy Shutter

Features

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard
HP Premium Quiet Keyboard, full-size, spill-resistant, backlit, a Programmable Key, with sperate numeric keypad, HP DuraKey, touchpad with glass surface, multi-touch gestures and taps enabled

Pointing Devices
Dual pointstick; Touchpad with multi-touch gestures enabled, taps enabled as default;
Microsoft Precision Touchpad Default Gestures Support

SOFTWARE AND SECURITY

Workstation ISV Certifications
See the latest list of certifications at: http://www.hp.com/go/isv

HP ZCENTRAL REMOTE BOOST SOFTWARE
The remote desktop solution for serious workstation users and their most demanding applications. Download at: http://www.hp.com/go/RGS

HP Performance Advisor
HP Performance Advisor enables optimal configuration of HP Mobile Workstations delivering stability and best performance. HP Performance Advisor will guide your system setup allowing a "custom" configuration that best matches the workstation to user requirements. Download at: http://www.hp.com/go/performanceadvisor

Software
Adobe Creative Cloud Bundle
Bing search for IE11
Buy Office
Data Science Stack
HP Admin
HP Connection Optimizer[20,9]
HP Cloud Recovery[21]
HP Easy Clean
HP PC Hardware Diagnostics
HP Privacy Settings
HP Hotkey Support
HP JumpStart
HP Noise Cancellation Software
HP Performance Advisor[8]
HP QuickDrop[22]
HP Recovery Manager
HP Remote Graphics Software
HP Smart Support[19]
HP Support Assistant[1]
HP ZCentral Remote Boost 2020 Software for Z workstation[23,2]
Native Miracast support
Tile Application

Security Management
Absolute persistence module[32,6]
HP BIOSphere Gen6[30,5]
HP Client Security Suite Gen7[16]
HP Device Access Manager
HP FingerPrint Sensor
HP Manageability Integration Kit[24,11]

Features

HP Power On Authentication
HP Secure Erase[31]
HP Security Manager
HP Secure Platform
HP Sure Click[26]
HP Sure Recover Gen4[28,13]
HP Sure Run[27]
HP Sure Sense[25,17]
HP Sure Start Gen6[29,14]
HP SureView Reflect;
HP Tamper Lock
Master Boot Record security;
Microsoft Defender[10]
Pre-boot authentication
Nano security lock slot[12]
Smartcard Reader - Alcor AU9560 (FIPS 201 Compliant)
Trusted Platform Module TPM 2.0 Embedded Security Chip with Windows 10 (Common Criteria EAL4+ Certified)(FIPS 140-2 Level 2 Certified)[33]
Windows Secured Core

BIOS Version
ISO/IEC 19678: 2015 (formerly NIST 800-147) compliant
UEFI version: 2.7

TPM
Model: Infineon SLB9670
Version: 7.85
Revision: TPM 2.0
FIPS 140-2 Compliant: Yes

Smartcard Reader
Model Number: Alcor AU9560
FIPS 201 Compliant: Yes

For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity**.**

[1] HP Support Assistant - Requires Windows and Internet Access.
[2] HP ZCentral Remote Boost Sender does not come preinstalled on Z Workstations but can be downloaded and run on all Z desktop and laptops without license purchase. With non-Z sender devices, purchase of perpetual individual license or perpetual floating license per simultaneously executing versions and purchase of ZCentral Remote Boost Software Support is required. ZCentral Remote Boost Sender for non-Z Hardware requires a license and Windows 10, RHEL/CentOS (7 or 8), or UBUNTU 18.04 or 20.04 LTS operating systems. macOS (10.14 or newer) operating system and ThinPro 7.2 are only supported on the receiver side. Requires network access. The software is available for download at hp.com/ZCentralRemoteBoost.
[5] HP BIOSphere Gen6 is available on select HP Pro, Elite and ZBook PCs. See product specifications for details. Features may vary depending on the platform and configurations. [6] Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
[8] HP Performance Advisor Software - HP Performance Advisor is ready and waiting to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: https://www8.hp.com/us/en/workstations/performance-advisor.html
[9] HP Connection Optimizer requires Windows 10.
[10] Microsoft Defender Opt in and internet connection required for updates.
[11] HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
[12] Nano Security lock slot is Lock sold separately.

Features

[13] HP Sure Recover Gen3: See product specifications for availability. Requires an open, wired network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. HP Sure Recover (Gen1) does not support platforms with Intel® Optane™.
[14] HP Sure Start Gen6 is available on select HP PCs with Intel processors. See product specifications for availability.
[15] For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
[16] HP Client Security Manager Gen5 requires Windows and is available on select HP Pro, Elite and ZBook PCs. See product specifications for details.
[17] HP Sure Sense requires Windows 10. See product specifications for availability.
[18] Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.
[19] HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: http://www.hp.com/smart-support. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.
[20] HP Connection Optimizer requires Windows 10.
[21] HP Cloud Recovery is available for Z by HP, HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630
[22] HP QuickDrop requires Internet access and Windows 10 PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.
[23] HP ZCentral Remote Boost Sender does not come preinstalled on Z Workstations but can be downloaded and run on all Z desktop and laptops without license purchase. With non-Z sender devices, purchase of perpetual individual license or perpetual floating license per simultaneously executing versions and purchase of ZCentral Remote Boost Software Support is required. ZCentral Remote Boost Sender for non-Z Hardware requires a license and Windows 10, RHEL/CentOS (7 or 8), or UBUNTU 18.04 or 20.04 LTS operating systems. macOS (10.14 or newer) operating system and ThinPro 7 are only supported on the receiver side. Requires network access. The software is available for download at hp.com/ZCentralRemoteBoost.
[24] HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
[25] HP Sure Sense is available on select HP PCs and is not available with Windows10 Home.
[26] HP Sure Click requires Windows 10. See https://bit.ly/2PrLT6A_SureClick for complete details.
[27] HP Sure Run is available on select HP PCs and requires Windows 10.
[28] HP Sure Recover Gen4 is available on select HP PCs and requires Windows 10 and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module.
[29] HP Sure Start Gen6 is available on select HP PCs.
[30] HP BIOSphere Gen6 features may vary depending on the platform and configuration.
[31] For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
[32] Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit: https://www.absolute.com/about/legal/agreements/absolute/.
[33] TPM 2.0 is limited on HP ThinPro/HP Smart Zero, and functionality is dependent upon use of a customer-enabled application that can locate the TPM chip.

Features

POWER

Power Supply

120 W Slim Smart external AC power adapter
150 W Slim Smart external AC power adapter
200 W UltraSlim Smart external AC power adapter

Primary Battery
HP Long Life 8-cell, 94 Wh Li-ion polymer[2,4]

Battery life[1]
MM18: TBD

120 W power adapter is configurable with Intel UMA graphics
150 W power adapter is configurable with NVIDIA® T1200 and RTX A2000 configurations
200 W power adapter is configurable with NVIDIA RTX A3000[3] or higher and AMD configurations

[1]Battery life will vary depending on the product model, configuration, loaded applications, features, use, wireless functionality and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See MobileMark18 battery benchmark https://bapco.com/products/mobilemark-2018/ for additional details.
[2]Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information.

[3] The HP custom vapor chamber (Z VaporForce) is only available on configurations with NVIDIA® RTX™ A3000 graphics or AMD Radeon graphics

[4]Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

ENVIRONMENTAL

ENERGY STAR® certified and EPEAT® registered where applicable.[1]

Low halogen[2]

[1] Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information.
[2] External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

Features

WEIGHTS & DIMENSIONS

Dimensions (w x d x h)
36.1 x 24.25 x 2.595 cm
14.21 x 9.55 x 1.0222 in

Weights
Starting at 2.35kg (5.18 lb)
Weight varies by configuration and components.

A deck: Anodized Aluminum + plastic antenna cover + magnesium inner structure
B deck: ; Plastic bezel + Touch has Corning® Gorilla ® Glass 5 (option)
C deck: Anodized Aluminum + magnesium inner structure
D deck: Magnesium Die Cast
E door: Magnesium Die Cast
Metal Alloy Hinges

Note:
A = Top
B = Panel Area
C = Keyboard/Touchpad surface
D = Bottom

PORTS/SLOTS

Left side[6]
1 RJ-45
1 SuperSpeed USB Type-A 5Gbps signaling rate (charging) [USB 3.1 Gen 1 Type A charging]
1 SuperSpeed USB Type-A 5Gbps signaling rate [USB 3.1 Gen 1 Type A]
1 headphone/microphone combo
1 smart card reader

Right side[6]
1 power connector
2 USB Type-C® (Thunderbolt™ 4[8], pass through support DisplayPort™ 1.4[2], USB 4, with BC 1.2)
1 Mini DisplayPort™ 1.4
1 HDMI 2.0b or HDMI 2.1 (depends on graphics selection)[1,3,4,5,7]
1 SD 7.0 Media Card Reader[9]

[1] HDMI port-cable not included.
[2] Mini DisplayPort™ 1.4 with discrete, 1.2 with UMA.
[3] HDMI 2.0b with NVIDIA T1200 and UMA (NVIDIA RTX™ A5000, RTX A4000, RTX A3000, RTX A2000, AMD Radeon Pro W6600M support HDMI 2.1 with FRL)
[4] When both USB Type-C® are in use, HDMI cannot be detected
[5] When one USB Type-C® is in use, HDMI can be detected if USB Type-C® in use is assigned to different channel
[6] When product is under heavy power loading, performance may be reduced to prevent battery drain. Disconnecting USB devices will restore system performance
[7] HDMI 2.1 not supported with T1200/UMA GPU
[8] SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4.
[9] SD4.0 cards will run at SD3 speed for any SD 7.0 host. This is the SD 7.0 standard. SD 7.0 cards availability is expected around August 2021 (may vary with card vendors)

SERVICE AND SUPPORT

Features

HP Services offers 3-year and 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.

[1]Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product. Consult your local HP Customer Support Center for details.

CERTIFICATION AND COMPLIANCE

Energy Efficiency Compliance	ENERGY STAR® certified
Energy Efficiency Compliance	EPEAT® GOLD

Technical Specifications – System Unit

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	**Nominal Operating Voltage**	19.5V	
	Average Operating Power(idle)	System in idle mode + max panel brightness	Adapter Safety test condition
	Discrete Graphics	80W	
	Max Operating Power	<200W	
Temperature	**Operating**	32° to 95° F (0° to 35° C) (Not Writing Optical)	
	Non-operating	-4° to 140° F (-20° to 60° C) (writing optical)	
Relative Humidity	**Operating**	10% to 90%, non-condensing	
	Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature	
Shock	**Operating**	40 G, 2 ms, half-sine	
	Non-operating	200 G, 2 ms, half-sine	
Random Vibration	**Operating**	0.75 grms	
	Non-operating	1.50 grms	
Maximum Altitude (unpressurized)	**Operating**	-50 to 10,000 ft. (-15.24 to 3,048 m)	
	Non-operating	-50 to 15,000 ft. (-15.24 to 12,192 m)	
Planned Industry Standard Certifications	**UL**	Yes	
	CSA	Yes	
	FCC Compliance	Yes	
	ENERGY STAR®	Yes	
	EPEAT®	Yes	
	ICES	Yes	
	Australia / NZ A-Tick Compliance	Yes	
	CCC	Yes	
	Japan VCCI Compliance	Yes	
	KCC	Yes	
	BSMI	Yes	
	CE Marking Compliance	Yes	
	MIL STD 810H	Yes	
	BNCI or BELUS	Yes	
	GOST	Yes	
	Saudi Arabian Compliance (ICCP)	Yes	
	UKRSERTCOMPUTER	Yes	

[1]Configurations of the HP ZBook Fury 15 G8 that are ENERGY STAR® qualified are identified as HP ZBook Fury 15 G8 ENERGY STAR on HP websites and on http://www.energystar.gov.

[2] EPEAT® registered where applicable. EPEAT registration varies by country. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at www.hp.com/go/options.

DISPLAYS

15.6" diagonal FHD IPS eDP1.2 anti-glare WLED-backlit and ambient light sensor 250 nits 45% CG (1920 x 1080)	**Outline Dimensions (W x H)**	350.96 x 216.65 mm (max)	
	Active Area	344.16 x 193.59 mm (typ.)	
	Weight	370 g (max)	
	Diagonal Size	15.6 inch	
	Thickness	3.2 mm (max)	
	Interface	eDP 1.2	
	Panel Technology	IPS	
	Surface Treatment	Anti-Glare	
	Touch Enabled	No	
	Refresh Rate	60 Hz	
	Brightness	250nits	
	Pixel Resolution	**Format**	1920 x 1080 (FHD)
		Configuration	RGB
	Backlight	LED	
	PPI	166	
	Color Gamut Coverage	45% CG	
	Color Depth	6 bits + Hi FRC	
	Viewing Angle	UWVA 85/85/85/85	
	All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.		
15.6" diagonal FHD IPS eDP1.3 + PSR anti-glare WLED-backlit and ambient light sensor 400 nits 72% CG (1920 x 1080)	**Outline Dimensions (W x H)**	350.96 x 216.75 mm (max)	
	Active Area	344.16 x 193.59 mm (typ.)	
	Weight	370 g (max)	
	Diagonal Size	15.6 inch	
	Thickness	3.2 mm (max)	
	Interface	eDP 1.3 + PSR	
	Panel Technology	IPS	
	Surface Treatment	Anti-Glare	
	Touch Enabled	No	
	Refresh Rate	60 Hz	
	Brightness	400 nits	
	Pixel Resolution	**Format**	1920 x 1080 (FHD)
		Configuration	RGB
	Backlight	LED	
	PPI	142	
	Color Gamut Coverage	72% CG	
	Color Depth	6 bits + Hi FRC	
	Viewing Angle	UWVA 85/85/85/85	
	All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.		

Technical Specifications – Displays

Next Gen HP SureView Reflect 15.6" diagonal FHD IPS eDP1.3 + PSR anti-glare WLED-backlit and ambient light sensor 1000 nits 72% CG (1920 x 1080)	**Outline Dimensions (W x H)**	349.52 x 205.39 (mm) max	
	Active Area	344.16 x 193.59 typ.	
	Weight	370g max.	
	Diagonal Size	15.6 inch	
	Thickness	2.6mm / 4.5mm max. (PCB)	
	Interface	eDP	
	Panel Technology	IPS	
	Surface Treatment	Anti-Glare	
	Touch Enabled	No	
	Contrast Ratio	1500:1 (typ.)	
	Refresh Rate	60Hz	
	Brightness	1000 nits	
	Pixel Resolution	**Pitch**	1920 x 1080 (FHD)
		Format	RGB
	Backlight	LED	
	PPI	141	
	Color Gamut Coverage	72% CG	
	Color Depth	8 bits	
	Viewing Angle	UWVA 85/85/85/85	
	All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.		
Next Gen HP Dream Color display 15.6" diagonal UHD IPS 120Hz eDP1.4 + PSR2 anti-glare BV LED-backlit and ambient light sensor 600 nits 100% DCI-P3 (3840 x 2160)	**Outline Dimensions (W x H)**	350.22 x 216.27 mm (max)	
	Active Area	344.22 x 193.62 (mm)	
	Weight	300g max.	
	Diagonal Size	15.6 inch	
	Thickness	2.6 (mm) max	
	Interface	eDP 1.4 + PSR2	
	Panel Technology	IPS	
	Surface Treatment	Anti-Glare	
	Touch Enabled	No	
	Contrast Ratio	1200:1 (typ.)	
	Refresh Rate	120Hz	
	Brightness	600 nits	
	Pixel Resolution	**Pitch**	3840 x 2160 (UHD)
		Format	RGB
	Backlight	LED	
	PPI	282	
	Color Gamut Coverage	100% DCI-P3	
	Delta E	<2	
	Color Depth	8 bits	
	Viewing Angle	UWVA 85/85/85/85	
	All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.		

Technical Specifications – Displays

15.6" diagonal UHD (3840 x 2160) IPS HDR 400 eDP1.4 + PSR2 WLED-backlit touch screen with Corning® Gorilla® Glass 5 and ambient light sensor 600 nits 100% DCI-P3	**Outline Dimensions (W x H)**	350.22 x 216.27 mm (max)	
	Active Area	344.22 x 193.62 (mm)	
	Weight	300g max.	
	Diagonal Size	15.6 inch	
	Thickness	2.6 (mm) max	
	Interface	eDP 1.4 + PSR2	
	Panel Technology	IPS	
	Surface Treatment	Anti-Glare	
	Touch Enabled	Yes	
	Contrast Ratio	1200:1 (typ.)	
	Refresh Rate	120Hz	
	Brightness	600 nits	
	Pixel Resolution	**Pitch**	3840 x 2160 (UHD)
		Format	RGB
	Backlight	LED	
	PPI	282	
	Color Gamut Coverage	100% DCI-P3	
	Delta E	<2	
	Color Depth	8 bits	
	Viewing Angle	UWVA 85/85/85/85	

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Technical Specifications – Storage

STORAGE AND DRIVES

256GB PCIe NVMe TLC M.2 2280 Solid State Drive	**Form Factor**	M.2 2280	
	Drive Weight	0.02 lb (10 g)	
	Capacity	256GB	
	NAND Type	TLC	
	Height	2.3 mm Max	
	Width	0.87 in (22 mm)	
	Interface	PCIe® Gen3 x4 NVMe™	
	Performance	**Maximum Sequential Read**	**Maximum Sequential Write**
		2580 MB/s～ 2600 MB/s	1000 MB/s～ 1100 MB/s
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security,TRIM; L1.2	
		For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. Slot 1 – 4 supports up to PCIe Gen 3 speeds	
256GB PCIe NVMe TLC M.2 2280 SED Opal 2 Solid State Drive	**Form Factor**	M.2 2280	
	Drive Weight	0.02 lb (10 g)	
	Capacity	256GB	
	NAND Type	TLC	
	Height	2.3 mm Max	
	Width	0.87 in (22 mm)	
	Interface	PCIe® Gen3 x4 NVMe™	
	Performance	**Maximum Sequential Read**	**Maximum Sequential Write**
		2580 MB/s～ 2600 MB/s	1000 MB/s～ 1100 MB/s
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security (Option); TCG Opal 2.0 ; TRIM; L1.2	
		For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. Slot 1 – 4 supports up to PCIe Gen 3 speeds	
512GB PCIe NVMe TLC M.2 2280 Solid State Drive	**Form Factor**	M.2 2280	
	Drive Weight	0.02 lb (10 g)	
	Capacity	512GB	
	NAND Type	TLC	
	Height	2.3 mm Max	
	Width	0.87 in (22 mm)	
	Interface	PCIe® Gen3 x4 NVMe™	
	Performance	**Maximum Sequential Read**	**Maximum Sequential Write**
		3400 MB/s	2956 MB/s
	Logical Blocks	1,000,215,216	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security,TRIM; L1.2	

Technical Specifications – Storage

		For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. Slot 1 – 4 supports up to PCIe Gen 3 speeds	
512TB PCIe NVMe TLC M.2 2280 SED Opal 2 Solid State Drive	**Form Factor**	M.2 2280	
	Drive Weight	0.02 lb (10 g)	
	Capacity	512GB	
	NAND Type	TLC	
	Height	2.3 mm Max	
	Width	0.87 in (22 mm)	
	Interface	PCIe® Gen3 x4 NVMe™	
	Performance	**Maximum Sequential Read**	**Maximum Sequential Write**
		3400 MB/s	2500 MB/s
	Logical Blocks	1,000,215,216	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security (Option); TCG Opal 2.0 ; TRIM; L1.2	
		For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. Slot 1 – 4 supports up to PCIe Gen 3 speeds	
1TB PCIe NVMe TLC M.2 2280 Solid State Drive	**Form Factor**	M.2 2280	
	Drive Weight	0.02 lb (10 g)	
	Capacity	1TB	
	NAND Type	TLC	
	Height	2.3 mm Max	
	Width	0.87 in (22 mm)	
	Interface	PCIe® Gen3 x4 NVMe™	
	Performance	**Maximum Sequential Read**	**Maximum Sequential Write**
		3480 MB/s	2800 MB/s
	Logical Blocks	2,000,409,264	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security,TRIM; L1.2	
	Available in RAID 1 config	Yes	
		For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. Slot 1 – 4 supports up to PCIe Gen 3 speeds	
2TB PCIe NVMe TLC M.2 2280 Solid State Drive	**Form Factor**	M.2 2280	
	Drive Weight	0.02 lb (10 g)	
	Capacity	2TB	
	NAND Type	TLC	
	Height	2.3 mm Max	
	Width	0.87 in (22 mm)	
	Interface	PCIe® Gen3 x4 NVMe™	
	Performance	**Maximum Sequential Read**	**Maximum Sequential Write**
		3180 MB/s	2920 MB/s

Technical Specifications – Storage

	Logical Blocks	3,907,029,168	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security,TRIM; L1.2	
	Available in RAID 1 config	Yes	
		For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software. Slot 1 – 4 supports up to PCIe Gen 3 speeds	
500GB SATA 2.5" HDD	**Form Factor**	2.5"	
	Drive Weight	0.21 lbs (95 g)	
	Capacity	500GB	
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface	ATA-8, SATA 3.0	
	Performance	**Maximum Sequential Read**	**Maximum Sequential Write**
		120MB/s	120MB/s
	Logical Blocks	976,773,168	
	Operating Temperature	32° to 140° F (0° to 60° C) [case temp]	
	Features	ATA Security; S.M.A.R.T., NCQ, Ultra DMA, DIPM, HIPM	
		Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.	
500GB SATA 2.5" SED HDD - FIPS-140-2	**Form Factor**	2.5"	
	Drive Weight	0.21 lbs (95 g)	
	Capacity	500GB	
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface	ATA-8, SATA 3.0	
	Performance	**Maximum Sequential Read**	**Maximum Sequential Write**
		120MB/s	120MB/s
	Logical Blocks	976,773,168	
	Operating Temperature	32° to 140° F (0° to 60° C) [case temp]	
	Features	ATA Security; S.M.A.R.T., NCQ, Ultra DMA, DIPM, HIPM	
		Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.	
1TB SATA 2.5" HDD	**Form Factor**	2.5"	
	Drive Weight	0.21 lbs (95 g)	
	Capacity	1TB	
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface	ATA-8, SATA 3.0	
	Performance	**Maximum Sequential Read**	**Maximum Sequential Write**
		120MB/s	120MB/s
	Logical Blocks	1,953,525,168	

Technical Specifications – Storage

	Operating Temperature	32° to 140° F (0° to 60° C) [case temp]	
	Features	ATA Security; S.M.A.R.T., NCQ, Ultra DMA, DIPM, HIPM	
		Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.	
2TB SATA 2.5" HDD	**Form Factor**	2.5"	
	Drive Weight	0.21 lbs (95 g)	
	Capacity	2TB	
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface	ATA-8, SATA 3.0	
	Performance	**Maximum Sequential Read**	**Maximum Sequential Write**
		100MB/s	100MB/s
	Logical Blocks	3,907,029,168	
	Operating Temperature	32° to 140° F (0° to 60° C) [case temp]	
	Features	ATA Security; S.M.A.R.T., NCQ, Ultra DMA, DIPM, HIPM	
		Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.	
1TB PCIe NVMe TLC M.2 2280 SED Opal 2 Solid State Drive	**Form Factor**	M.2 2280	
	Drive Weight	0.02 lb (10 g)	
	Capacity	1TB	
	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Interface	PCIe® Gen3 x4 NVMe™	
	Performance	**Maximum Sequential Read**	**Maximum Sequential Write**
		Up to 3500 MB/s	Up to 3000 MB/s
	Logical Blocks	2,000,409,264	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security (Option); TCG Opal 2.0; TRIM; L1.2;	
		Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.	
2TB PCIe NVMe TLC M.2 2280 SED Opal 2 Solid State Drive	**Form Factor**	M.2 2280	
	Drive Weight	0.02 lb (10 g)	
	Capacity	2TB	
	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Interface	PCIe® Gen3 x4 NVMe™	
	Performance	**Maximum Sequential Read**	**Maximum Sequential Write**

Technical Specifications – Storage

		Up to 3500 MB/s	Up to 3000 MB/s
	Logical Blocks	4,000,797,360	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security (Option); TCG Opal 2.0; TRIM; L1.2;	
		Notes: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.	
SSD 256GB 2280 PCIe-4x4 NVMe Three Layer Cell	**Form Factor**	M.2 2280	
	Capacity	256 GB	
	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (<10 g)	
	Interface	PCIe® Gen4 x4 NVMe™	
	Performance	**Maximum Sequential Read**	**Maximum Sequential Write**
		Up to 6,400 MB/s	Up to 2,700 MB/s
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	Pyrite 2.0; TRIM; L1.2;	
		Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.	
SSD 512GB 2280 PCIe-4x4 NVMe Three Layer Cell	**Form Factor**	M.2 2280	
	Capacity	512 GB	
	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (<10 g)	
	Interface	PCIe® Gen4 x4 NVMe™	
	Performance	**Maximum Sequential Read**	**Maximum Sequential Write**
		Up to 6,600 MB/s	Up to 5,100 MB/s
	Logical Blocks	1,000,215,216	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	Pyrite 2.0; TRIM; L1.2;	
		Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.	
SSD 1TB 2280 PCIe-4x4 NVMe Three Layer Cell	**Form Factor**	M.2 2280	
	Capacity	1TB	
	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	

Technical Specifications – Storage

	Width	0.87 in (22 mm)	
	Weight	0.02 lb (<10 g)	
	Interface	PCIe® Gen4 x4 NVMe™	
	Performance	**Maximum Sequential Read**	**Maximum Sequential Write**
		Up to 7,100 MB/s	Up to 5,200 MB/s
	Logical Blocks	2,000,409,264	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	Pyrite 2.0; TRIM; L1.2;	
		Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.	
SSD 2TB 2280 PCIe-4x4 NVMe Three Layer Cell	**Form Factor**	M.2 2280	
	Capacity	2TB	
	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (<10 g)	
	Interface	PCIe® Gen4 x4 NVMe™	
	Performance	**Maximum Sequential Read**	**Maximum Sequential Write**
		Up to 7,100 MB/s	Up to 5,200 MB/s
	Logical Blocks	4,000,797,360	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	Pyrite 2.0; TRIM; L1.2;	
		Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.	
256GB PCIe-4x4 2280 NVME Self Encrypted OPAL2 Three Layer Cell Solid State Drive	**Form Factor**	M.2 2280	
	Capacity	256 GB	
	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (<10 g)	
	Interface	PCIe® Gen4 x4 NVMe™	
	Performance	**Maximum Sequential Read**	**Maximum Sequential Write**
		6,400 MB/s	2,700 MB/s
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security (Option); TCG Opal 2.0; TRIM; L1.2;	
		Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.	

Technical Specifications – Storage

512GB PCIe-4x4 2280 NVME Self Encrypted OPAL2 Three Layer Cell Solid State Drive	**Form Factor**	M.2 2280	
	Capacity	512 GB	
	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (<10 g)	
	Interface	PCIe® Gen4 x4 NVMe™	
	Performance	**Maximum Sequential Read**	**Maximum Sequential Write**
		6,600 MB/s	5,100 MB/s
	Logical Blocks	1,000,215,216	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	ATA Security (Option); TCG Opal 2.0; TRIM; L1.2;	
		Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.	

Technical Specifications – Networking

NETWORKING/COMMUNICATION

Intel i219LM 10/100/1000 Integrated NIC vPro™	**Connector**	RJ-45
	System Interface	PCI(Intel proprietary) + SMBus
	Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
	Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling(Hash Mode Only) Jumbo Frame 9K
	Power consumption	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
	Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
	Management Interface	Auto MDI/MDIX Crossover cable detection
	IT Manageability	Wake-on-LAN from modem standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
	Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel i219v 10/100/1000 Integrated NIC non-vPro™	**Connector**	RJ-45
	System Interface	PCI(Intel proprietary) + SMBus
	Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10, 100 & 1000 Mbit/s
	IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support

Technical Specifications – Networking

	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet) IEEE 802.3i 10BASE-T IEEE 802.3u 100BASE-TX IEEE 802.3ab 1000BAE-T IEEE 802.3bz 2.5GBASE-T
Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling(Hash Mode only) Jumbo Frame 9K
Power consumption	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from modem standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status

NFC (Near Field Communication) module (optional)

Dimensions (L x W x H)	Module 50 mm by 23 mm by 2.89 mm
Chipset	SiM3U156+SiM3U154+AMS3911
System interface	USB 2.0
System interface (I/O)	Audio signal output on card read
NFC RF standards (In reading CSN)	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1
NFC Forum Support	Tag Type 1, Type 2, Type3 and Type 4 in reading CSN
Reader Mode	13.56MHz: ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Topaz cards

Technical Specifications – Networking

		HID iClass ISO 125kHz: HID Prox UID AWID UID CASI-RUSCO UID EM 410x UID Indana ASP/ASP+ UID	
	Frequency	13.56MHz and 125kHz	
	NFC Modes Supported	Reader	
	Raw RF Data Rates	106, 212 kbps	
	Operating temperature	-30°C to 70°C	
	Storage temperature	-40°C to 80°C	
	Humidity	10-90% operating 5-95% non-operating	
	Supply Operating voltage	4.35 to 5.25 Volts	
	Power Consumption	**Mode**	Power Consumption, Typical
		Polling	75mA
		Communication	85mA
	Antenna	13.56MHz/125kHz combo antenna. Antenna connector, 0.5mm pitch, 16pin connector FPC.	
Intel Wi-Fi 6 AX201 + BT5.2 (802.11ax 2x2, non-vPro, supporting gigabit data rate*) non-vPro**	**Wireless LAN Standards**	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v	
	Interoperability	Wi-Fi certified	
	Frequency Band	802.11b/g/n/ax • 2.402 – 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz	
	Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)	

Technical Specifications – Networking

	• 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM , 1024QAM
Security[1]	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 and WPA3 certification • IEEE 802.11i • WAPI
Network Architecture **Models**	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power[2]	• 802.11b : +18.5dBm minimum • 802.11g : +17.5dBm minimum • 802.11a : +18.5dBm minimum • 802.11n HT20(2.4GHz) : +15.5dBm minimum • 802.11n HT40(2.4GHz) : +14.5dBm minimum • 802.11n HT20(5GHz) : +15.5dBm minimum • 802.11n HT40(5GHz) : +14.5dBm minimum • 802.11ac VHT80(5GHz) : +11.5dBm minimum • 802.11ac VHT160(5GHz) : +11.5dBm minimum • 802.11ax HT40(2.4GHz) : +10dBm minimum • 802.11ax VHT160(5GHz) : +10dBm minimum
Power Consumption	• Transmit mode 2.0 W • Receive mode 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode 50 mW (WLAN unassociated) • Connected Standby 10mW • Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity[3]	•802.11b, 1Mbps : -93.5dBm maximum •802.11b, 11Mbps : -84dBm maximum • 802.11a/g, 6Mbps : -86dBm maximum • 802.11a/g, 54Mbps : -72dBm maximum • 802.11n, MCS07 : -67dBm maximum • 802.11n, MCS15 : -64dBm maximum • 802.11ac, MCS0 : -84dBm maximum • 802.11ac, MCS9 : -59dBm maximum •802.11ax, MCS11(HT40): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum
Antenna Type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface

Technical Specifications – Networking

Dimensions	1. Type 2230 : 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Weight	1. Type 2230 : 2.8g 2. Type 126: 1.3g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio Off; LED Off – Radio ON	

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1/5.2 Wireless Technology

Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Link Topology	
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP)

		Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

*GbE - The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

**Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.

Intel Wi-Fi 6 AX201 + BT5.2 (802.11ax 2x2, vPro, supporting gigabit data rate*) vPro**	**Wireless LAN Standards**	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi certified
	Frequency Band	802.11b/g/n/ax • 2.402 – 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
	Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) • 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
	Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM , 1024QAM
	Security[1]	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 and WPA3 certification

Technical Specifications – Networking

	• IEEE 802.11i • WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power[2]	• 802.11b : +18.5dBm minimum • 802.11g : +17.5dBm minimum • 802.11a : +18.5dBm minimum • 802.11n HT20(2.4GHz) : +15.5dBm minimum • 802.11n HT40(2.4GHz) : +14.5dBm minimum • 802.11n HT20(5GHz) : +15.5dBm minimum • 802.11n HT40(5GHz) : +14.5dBm minimum • 802.11ac VHT80(5GHz) : +11.5dBm minimum • 802.11ac VHT160(5GHz) : +11.5dBm minimum • 802.11ax HT40(2.4GHz) : +10dBm minimum • 802.11ax VHT160(5GHz) : +10dBm minimum
Power Consumption	• Transmit mode :2.0 W • Receive mode :1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode :50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity[3]	•802.11b, 1Mbps : -93.5dBm maximum •802.11b, 11Mbps : -84dBm maximum • 802.11a/g, 6Mbps : -86dBm maximum • 802.11a/g, 54Mbps : -72dBm maximum • 802.11n, MCS07 : -67dBm maximum • 802.11n, MCS15 : -64dBm maximum • 802.11ac, MCS0 : -84dBm maximum • 802.11ac, MCS9 : -59dBm maximum •802.11ax, MCS11(HT40): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum
Antenna Type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface
Dimensions	1. Type 2230 : 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230 : 2.8g 2. Type 126: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C)
Humidity	Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing)
Altitude	Operating 0 to 10,000 ft (3,048 m) Non-operating 0 to 50,000 ft (15,240 m)

Technical Specifications – Networking

LED Activity	LED Amber – Radio OFF; LED White – Radio ON
HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1/5.2 Wireless Technology	
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Link Topology	
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

*GbE - The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

**Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 are draft specifications and are not final. If the final specifications differ from

the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.

Intel® XMM™ 7360 LTE-Advanced CAT9 (Pandora)*

Technology/Operating bands	FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66). TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41). HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz
Wireless protocol standards	3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to 450Mbps; UL 20MHz throughput up to 50Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
GPS	Standalone, A-GPS (MS-A, MS-B)
GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz
Maximum data rates	LTE: 450 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm
Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
Form Factor	M.2, 3042-S3 Key B
Weight	5.8 g
Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm

* Mobile Broadband is an optional feature and requires configuration at purchase. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Near Field Communications Controller (optional)

Dimensions (L x W x H)	Module 25 mm by 10 mm by 2.0 mm
Chipset	NPC100
System interface	I2C
NFC RF standards	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2
NFC Forum Support	Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2
Reader (PCD-VCD) Mode(1)	ISO/IEC 14443 A ISO/IEC 14443 B

Technical Specifications – Networking

	ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards		
Card Emulation (PICC-VICC) Mode(1)	ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa		
Frequency	13.56 MHz		
NFC Modes Supported	Reader/Writer, Peer-to-Peer		
Raw RF Data Rates	106, 212, 424, 848 kbps		
Operating temperature	0°C to 70°C		
Storage temperature	-20°C to 125°C		
Humidity	10-90% operating 5-95% non-operating		
Supply Operating voltage	4.35 to 5.25 Volts		
I/O Voltage	1.8V or 3.3V		
Power Consumption	**Booster enable,**	VBAT= 3.3V,	
	VCC_BOOST = 5V) Mode Power Consumption, Typical	**Polling**	7.3 mA
		Detected Test Tag Type 1	Total 283.8 mA Net Module 236.8 mA
		Detected Test Tag Type 2	Total 288.8 mA Net Module 241.8 mA
		Detected Test Tag Type 3	Total 287.7 mA Net Module 240.7 mA
		Detected Test Tag Type 4	Total 282.3 mA Net Module 235.3 mA
Antenna	Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is external to module.		

Technical Specifications – Power

POWER

120 Watt Slim Smart AC Adapter	**Dimensions**	138x68.5x25.4mm	
	Weight	unit: 350g +/- 10g	
	Input	**Input Efficiency**	88% at 115 Vac and 89% at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	1.7 A at 90 Vac and Maximum Load
	Output	**Output power**	120W
		DC output	19.5V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<18.0A
	Connector	C5	
	Environmental Design	**Operating temperature**	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	5% to 95%
		Storage Humidity	5% to 95%
	EMI and Safety Certifications	Eg: *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.	

*Can only be configured with Intel UMA Graphics option

150 Watt Slim Smart AC Adapter	**Dimensions**	138x66x22mm	
	Weight	unit: 325g +/- 10g	
	Input	**Input Efficiency**	88% at 115 Vac and 89% at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	2.7 A at 90 Vac and Maximum Load
	Output	**Output power**	150W
		DC output	19.5V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<16.0A
	Connector	C5	
	Environmental Design	**Operating temperature**	32° to 95° F (0° to 35° C)

Technical Specifications – Power

		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	5% to 95%
		Storage Humidity	5% to 95%
	EMI and Safety Certifications	Eg: *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.	

*Can only be configured with NVIDIA T1200 and A2000 Graphics option

200 Watt UltraSlim Smart AC Adapter	**Dimensions**	152x73x23.5mm	
	Weight	unit: 530g +/- 10g	
	Input	**Input Efficiency**	88% at 115 Vac and 89% at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	2.9 A at 90 Vac and Maximum Load
	Output	**Output power**	200W
		DC output	19.5V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<16.0A
	Connector	C13	
	Environmental Design	**Operating temperature**	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	5% to 95%
		Storage Humidity	5% to 95%
	EMI and Safety Certifications	Eg: *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 100,000 hours at 25°C ambient condition.	

*Can only be configured with RTX A3000, RTX A4000, RTX A5000 Graphics and Radeon W6600M Graphics option

Technical Specifications – Power

HP Long Life 8-cell Polymer (94Wh) Battery	**Cells/Type**	8 cell	
	Energy	Voltage	11.55V
		Amp-hour capacity	4.15Ah
	Temperature	Operating (Charging)	0˚ to 60˚ C
		Operating (Discharging)	-20˚ to 70˚ C
	Fuel Gauge LED	NA	
	Warranty	Depends on system offering	
	Optional Travel Battery Available	No	

*Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

Refer to http://www.hp.com/support/batterywarranty/ for battery warranty information.

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- US Federal Energy Management Program (FEMP)
- EPEAT Gold registered in the United States. See http://www.epeat.net for registration status in your country.
- TCO certified
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label*

Sustainable Impact Specifications

• 10% post-consumer recycled plastic
• External Power Supply 90% Efficiency
• Low halogen
• Outside Box and corrugated cushions are 100% sustainably sourced and recyclable
• Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable
• Bulk packaging available

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a “Typically Configured Notebook”.

Energy Consumption (in accordance with US ENERGY STAR® test method)	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)	13.73 W	13.82 W	13.88 W
Normal Operation (Long idle)	1.68 W	1.80 W	1.76 W
Sleep	1.68 W	1.80 W	1.76 W
Off	0.43 W	0.44 W	0.42 W

NOTE:
Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)	47 BTU/hr	47 BTU/hr	47 BTU/hr
Normal Operation (Long idle)	6 BTU/hr	6 BTU/hr	6 BTU/hr
Sleep	6 BTU/hr	6 BTU/hr	6 BTU/hr
Off	1 BTU/hr	1 BTU/hr	1 BTU/hr

***NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Technical Specifications – Environmental

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L_{WAd}, bels)	Sound Pressure (L_{pAm}, decibels)
Typically Configured – Idle	2.6	13.8
Fixed Disk – Random writes	2.7	15.8
Optical Drive – Sequential reads	2.9	19.5

Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product is 94% recycle-able when properly disposed of at end of life.

Packaging Materials

External:	PAPER/Corrugated	306 g
Internal:	PAPER/Molded pulp	181 g
	PLASTIC/Polyethylene low density	13 g
	PLASTIC/polypropylene	5 g

The plastic packaging material contains at least 57% recycled content.

The corrugated paper packaging materials contains at least 59% recycled content.

RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html

):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

Technical Specifications – Environmental

HP Inc. Corporate Environmental Information	For more information about HP's commitment to the environment: Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
footnotes	• Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard. • External power supplies, WWAN modules, power cords, cables and peripherals excluded. • 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers. • Fiber cushions made from 100% recycled wood fiber and organic materials.

Options and Accessories (sold separately and availability may vary by country)

Type	Description	Part #
Displays	HP Z32 31.5” 4k UHD Display	1AA81A8#XXX
	HP Z38c 37.5” Curved Display	Z4W65A8#XXX
Case	HP Essential Top Load Case (up to 15.6")	H2W17AA
	HP Essential Backpack (up to 15.6")	H1D24AA
	HP Executive 17.3 Backpack	6KD05AA
	HP Executive 17.3 Top Load	6KD08AA
	HP Business Case(up to 15.6")	2SC66AA
	HP Executive 15.6 Midnight Top Load	1KM15AA
	HP Exec 15.6 Midnight Backpack	1KM16AA
	HP Executive 15.6 Black Leather Top Load	1LG83AA
	HP 17.3 Business Backpack	2SC67AA
	HP 17.3 Business Slim Top Load	2UW02AA
	HP Prelude Pro Recycle Backpack	1X644AA
	HP Prelude Pro Recycle Top Load	1X645AA
	HP Executive 15.6 Top Load	6KD06AA
	HP Executive 15.6 Backpack	6KD07AA
	HP Executive 15.6 Leather Top Load	6KD09AA
	HP Prelude 15.6 Top Load	1E7D7AA
	HP Renew Business 17.3 Laptop Backpack	3E2U5AA
	HP Renew Business 17.3 Laptop Bag	3E2U6AA
	HP Renew Business 15.6 Laptop Bag	3E5F8AA
Docking Accessories	HP TB Audio Module (comp with Hook dock)	3AQ21AA
	HP TB Dock G2 Combo Cable (this is 230W) comp with Hook dock	3XB96AA
Docking station	HP TB Dock G2 w/ Combo Cable (this is 230W)	3TR87AA
	HP Thunderbolt Dock 230W G2	2UK38AA
	HP USB-C/A Universal Dock G2 Power Not Supported on Mobile Workstations	5TW13AA
	HP USB-C Dock G5 Power Not Supported on Mobile Workstation	5TW10AA
	HP TB Dock 120W G2 w/ Audio	3YE87AA
Input/Output - Mice	HP Comfort Grip Wireless Mouse (See Link 5 Tab)	H2L63AA
	HP 3-button USB Laser Mouse	H4B81AA
	HP Bluetooth Travel Mouse	6SP30AA
	HP USB Travel Mouse	G1K28AA
	HP Wireless Premium Mouse (See Link 5 Tab)	1JR31AA
	HP Elite Presenter Mouse	2CE30AA
	HP Comfort Grip Wireless Mouse (See Link 5 Tab)	H2L63AA
	HP X4000b Bluetooth Mouse	H3T50AA
	HP Wired 320M Mouse	9VA80AA
	HP 435 Multi-Device Wireless Mouse	3B4Q5AA

Options and Accessories (sold separately and availability may vary by country)

Input/Output - Keyboard	HP Wired Desktop 320MK Mouse and Keyboard	9SR36AA
	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP 320K Wired Keyboard	9SR37AA
	HP Wireless Rechargeable 950MK Mouse and Keyboard	3M165AA
Input/Output - Adapter	HP USB-C to USB-A Hub	Z6A00AA
	HDMI to VGA Adapter	H4F02AA
	HP HDMI to DVI Adapter	F5A28AA
	HP USB-C to USB 3.0 Adapter	N2Z63AA
	HP USB-C to DisplayPort Adapter	N9K78AA
	HP USB-C to VGA Adapter	N9K76AA
	HP Single miniDP-to-DP Adapter Cable	2MY05AA
	HP Elite USB-C Hub	4WX89AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
Collaboration	HP BT UC Wireless Duo Headset	W3K09AA
Memory	HP 8GB DDR4 3200 1.2v SODIMM Memory	286H8AA
	HP 16GB DDR4 3200 1.2v SODIMM Memory	286J1AA
	HP 32GB DDR4 2666 SODIMM Memory	6NX83AA
	HP 8GB DDR4 2666 SODIMM ECC Memory	4UY11AA
	HP 16GB DDR4 2666 SODIMM ECC Memory	4UY12AA
Power - A/C Adapter	HP 150W 4.5 mm Smart AC Power Adapter	4SC18AA
	HP 200W 4.5 mm AC Power Adapter	4SC19AA
	HP ZBook 200W Slim Smart 4.5mm AC Adapter	49J06AA
Power - Battery	HP ZBook Fury G7/G8 94Whr Battery	4A1H3AA
Security	HP Sure Key Cable Lock	6UW42AA
	HP Nano Keyed Cable Lock	1AJ39AA
	HP Nano Dual Head Keyed Cable Lock	1AJ41AA
Storage - External	HP USB DVD-Writer ODD	Y3T76AA
Storage – HDD 2.5”	HP 500GB 7200 RPM HDD 2.5”	4A1H1AA
	HP 1TB 7200 RPM HDD 2.5”	4A1H2AA
	HP 2TB 5400 RPM HDD 2.5”	4A1H3AA
Storage - SS M2	HP 1TB 2280 PCIe-3x4 NVME TLC M.2 SSD	6SK99AA
	HP 2GB 2280 PCIe-3x4 NVME TLC M.2 SSD	6SL00AA
	HP 256GB PCIe-3x4 NVME M.2 SSD	1D0H6AA
	HP 512GB PCI-e 3x4 NVMe M2 SSD	1D0H7AA
	HP ZBook Fury G7/G8 HDD & SSD Brackets	48Z98AA

Options and Accessories (sold separately and availability may vary by country)

WWAN	HP XMM 7360 LTE-Advance WWAN	3FB01AA

Copyright © 2021 HP Development Company, L.P. The information contained herein is subject to change without notice. The only warranties for HP products are set forth in the express limited warranty statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein.
Intel, Core, and Celeron, Thunderbolt and vPro are registered trademarks or trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries. Bluetooth is a registered trademark of its proprietor used by HP Inc. under license. AMD, FirePro, and Enduro are trademarks of Advanced Micro Devices, Inc. Adobe is a trademark of Adobe Systems Incorporated. Microsoft and Windows are U.S. registered trademarks of Microsoft Corporation in the United States and/or other countries. Qualcomm and Snapdragon are trademarks of Qualcomm, Inc. SD, SDHC, and SDXC are trademarks or registered trademarks of SD-3C in the United States, other countries or both. USB Type-C and USB-C are trademarks of USB Implementers Forum. ENERGY STAR® is a registered trademark mark of the U.S. Environmental Protection Agency.

Date of change:	Version History:		Description of change:
	From v1 to v2		